

**IN THE CLAIMS:**

Claim 10 has been amended herein. All of the pending claims 1 through 13 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

**Listing of Claims:**

1. (previously presented) A method for locating a plurality of packaged integrated circuit semiconductor devices on a board having a multi-port connector having at least one port comprising:  
locating a first packaged semiconductor device having a plurality of terminals to a portion of the board;  
attaching a second packaged semiconductor device having a plurality of terminals to a portion of the first packaged semiconductor device; and  
connecting a multiconductor flexible assembly between at least one terminal of the plurality of terminals on the first packaged semiconductor device and at least one terminal of the plurality of terminals of the second packaged semiconductor device and the at least one port of the multi-port connector.
2. (original) The method of claim 1, wherein the multiconductor flexible assembly includes tape.
3. (original) The method of claim 1, wherein the multiconductor flexible assembly includes epoxy.
4. (original) The method of claim 1, wherein the multiconductor flexible assembly includes an extruded multiconductor flexible assembly.

5. (original) The method of claim 1, wherein the multiconductor flexible assembly comprises an extrusion.

6. (original) The method of claim 5, wherein the extrusion is cut to form the multiconductor flexible assembly.

7. (original) The method of claim 6, wherein at least one conductor is exposed during the cutting of the extrusion to form the multiconductor flexible assembly.

8. (original) The method of claim 6, wherein at least two conductors are exposed during the cutting of the extrusion to form the multiconductor flexible assembly.

9. (previously presented) The method of claim 1, wherein the multiconductor flexible assembly includes a plurality of conductors separated by insulating material located therebetween.

10. (currently amended) A method of locating a plurality of ~~a~~ a packaged semiconductor device assemblies on a support surface having a first multiconductor assembly on the support surface, the first multiconductor assembly having at least one contact pad, comprising:

providing a first packaged semiconductor device having bond pads thereon;

providing a second packaged semiconductor device having bond pads thereon;

locating the first packaged semiconductor device on a portion of the first multiconductor assembly having at least one bond pad of the first packaged semiconductor device contacting the at least one contact pad of the first multiconductor assembly;

positioning ~~the~~ a second multiconductor flexible assembly on a portion of the first packaged semiconductor device, the second multiconductor flexible assembly including at least one contact pad; and

positioning ~~a~~the second packaged semiconductor device having at least one bond pad thereof contacting the at least one contact pad of the second multiconductor flexible assembly.

11. (original) The method of claim 10, wherein the at least one contact pad of the first multiconductor assembly and the at least one contact pad of the second multiconductor flexible assembly are each connected to conductors which are, in turn, connected to a multiconductor port supported by the support surface.

12. (original) A method for locating a semiconductor assembly on a board having a multiconductor port thereon comprising:  
providing a first packaged semiconductor device having a plurality of bond pads;  
providing a first multiconductor assembly having a plurality of contact pads thereon;  
providing a second packaged semiconductor device having a plurality of bond pads thereon;  
providing a second multiconductor assembly having a plurality of contact pads thereon;  
locating the first packaged semiconductor device to a portion of the board;  
positioning the first multiconductor assembly on the first packaged semiconductor device having at least one contact pad of the plurality of contact pads of the first multiconductor assembly contacting at least one bond pad of the plurality of bond pads of the first packaged semiconductor device;  
positioning the second packaged semiconductor device on a portion of the first multiconductor assembly; and  
positioning the second multiconductor assembly on a portion of the second packaged semiconductor device having at least one contact pad of the plurality of contact pads of the second multiconductor assembly contacting at least one bond pad of the plurality of bond pads of the second packaged semiconductor device.

13. (original) The method of claim 12, wherein the at least one contact pad of the plurality of contact pads of the first multiconductor assembly and the at least one contact pad of the plurality of contact pads of the second multiconductor assembly are connected to conductors which are, in turn, connected to the multiconductor port on the board.